

# SLI-570x/SLA-570x Series

Data Sheet

#### **■** Features

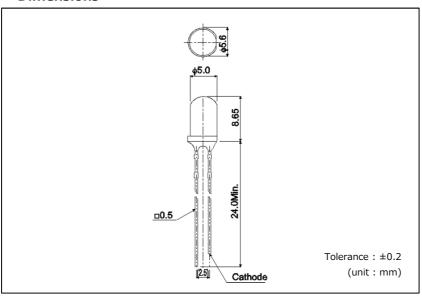
Viewing angle 2θ 1/2 : 20° (SLI-570 Series)
Viewing angle 2θ 1/2 : 25° (SLA-570 Series)

High brightness

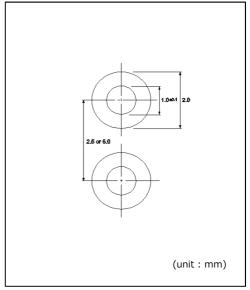


# Outline

#### **■** Dimensions



#### **■** Recommended Solder Pattern



#### **■** Specifications

				Abso	olute Ma	ximum F	Ratings (Ta=25	°C)		•	Electr	ical and	l Optical Characteristi	cs (Ta=	=25°C)	•	•
Part No.	Chip Structure	Emitting	Power	Forward	Peak Forward	Reverse		Storage Temp.	Forward '	Voltage V <sub>F</sub>	Reverse	Current I <sub>R</sub>	Peak Wavelength	ıλ <sub>P</sub>	Lumin	ous Inte	nsity I <sub>V</sub>
Tarrivo.	omp otractaro	Color	Dissipation	Current	Current	Voltage		Otorage Temp.	Тур.	I <sub>F</sub>	Max.	$V_R$	Тур.	I <sub>F</sub>	Min.	Тур.	I <sub>F</sub>
			P <sub>D</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)	$V_R(V)$	T <sub>opr</sub> (°C)	T <sub>stg</sub> (°C)	(V)	(mA)	(µA)	(V)	(nm)	(mA)	(mcd)	(mcd)	(mA)
SLI-570UT		Red											630		900	3000	
SLI-570U2T		Red							1.9				630		2200	4000	
SLI-570DT	AlGalnP	Orange	125	50	200* <sup>2</sup>	9	-30~+85	-40~+100		20	100	9	611	20	900	3000	20
SLI-570YT		Yellow											591	20	610	2500	
SLI-570Y2T		reliow							2.1				591		2200	5200	
SLA-570MT	GaP	Yellowish green	75	25	60* <sup>1</sup>	4	-25~+85	-30~+100	2.3	20	10	4	563		200	470	

\*1 : Duty1/5, 200Hz, \*2 :Duty1/10 1kHz

#### **■ Electrical Characteristics Curves**

Reference

Fig.1 Forward Current
- Forward Voltages

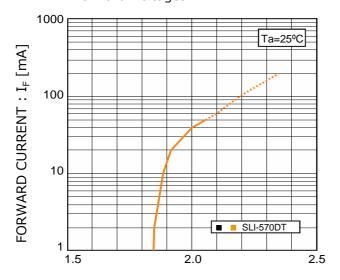
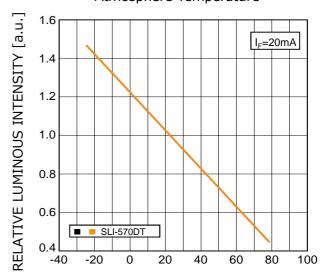


Fig.2 Luminous Intensity - Atmosphere Temperature



FORWARD VOLTAGE: V<sub>F</sub> [V]

ATMOSPHERE TEMPERATURE: Ta [°C]

Fig.3 Luminous Intensity - Forward Current

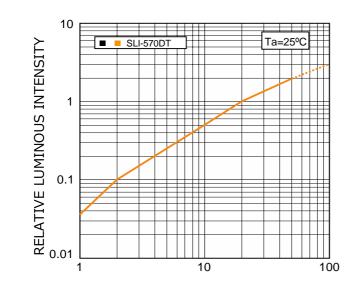
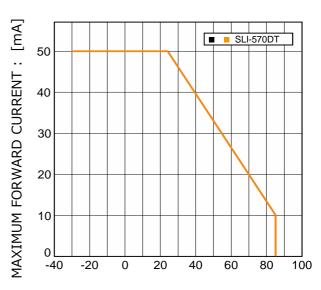


Fig.4 Derating



FORWARD CURRENT :  $I_F$  [mA]

AMBIENT TEMPERATURE : Ta [°C]

#### **■ Electrical Characteristics Curves**

Reference

Fig.1 Forward Current

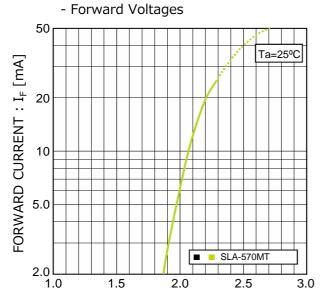
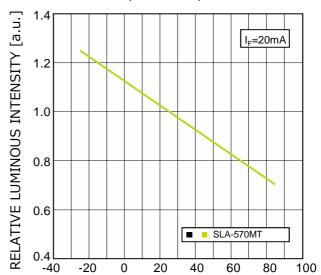


Fig.2 Luminous Intensity - Atmosphere Temperature



FORWARD VOLTAGE: V<sub>F</sub> [V]

ATMOSPHERE TEMPERATURE : Ta [°C]

Fig.3 Luminous Intensity - Forward Current

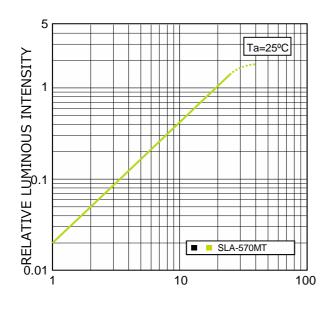
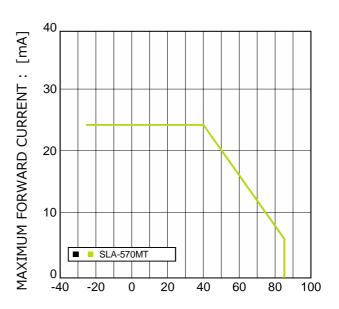


Fig.4 Derating



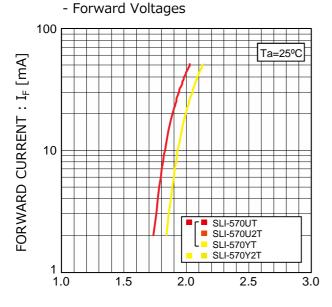
FORWARD CURRENT :  $I_F$  [mA]

AMBIENT TEMPERATURE : Ta [°C]

#### **■ Electrical Characteristics Curves**

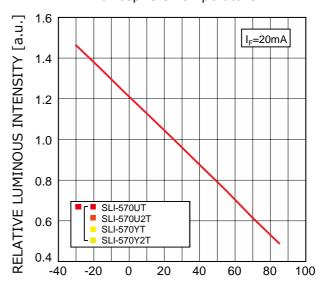
Reference

Fig.1 Forward Current



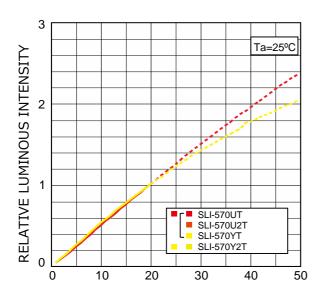
FORWARD VOLTAGE :  $V_F[V]$ 

Fig.2 Luminous Intensity - Atmosphere Temperature



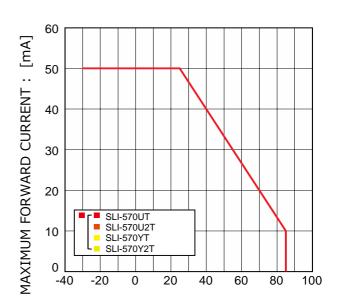
ATMOSPHERE TEMPERATURE : Ta [°C]

Fig.3 Luminous Intensity - Forward Current



FORWARD CURRENT :  $I_F$  [mA]

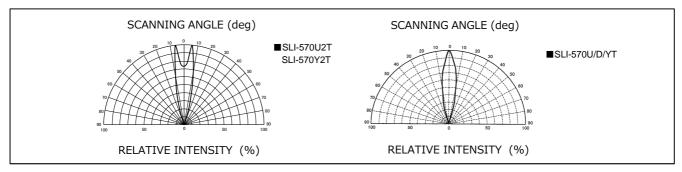
Fig.4 Derating

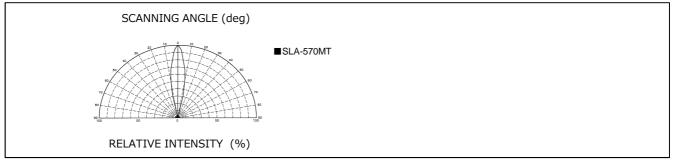


AMBIENT TEMPERATURE : Ta [°C]

#### **■ Viewing Angle**

Reference





 $(Ta=25^{\circ}C, I_F=20mA)$ 

### ■ Rank Reference of Brightness\*

\*Measurement tolerance: ±10%

Red(U)

Rank	XE	XF	XG	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	47~ 68	8 68~ 100	100~150	150~220	220~330	330~470	470~680	680~1000	1000~1500	1500~2200	2200~ 3300	3300~4700	4700~6800	6800~10000	10000~15000
SLI-570UT															
SLI-570U2T															

Orange(D) (Ta=25°C, I<sub>F</sub>=20mA)

Rank	XE	XF	XG	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	47~ 68	68~ 100	100~150	150~220	220~330	330~470	470~680	680~1000	1000~1500	1500~2200	2200~ 3300	3300~4700	4700~6800	6800~10000	10000~15000
SLI-570DT															

Yellow (Y)  $(Ta=25^{\circ}C, I_F=20mA)$ 

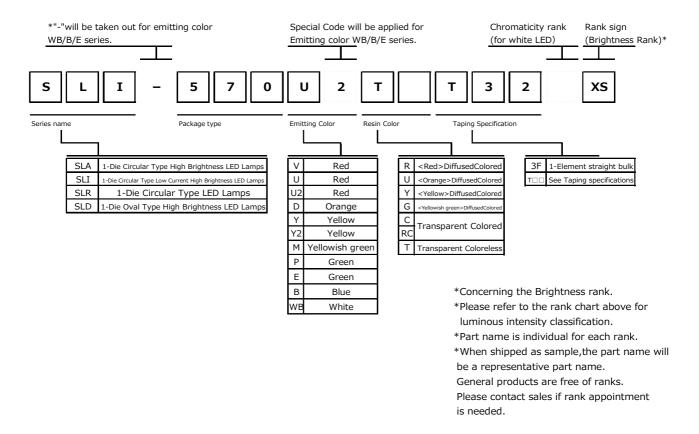
Rank	XE	XF	XG	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	47~ 68	68~ 100	100~150	150~220	220~330	330~470	470~680	680~1000	1000~1500	1500~2200	2200~ 3300	3300~4700	4700~6800	6800~10000	10000~15000
SLI-570YT															
SLI-570Y2T															

Yellowish Green(M)

 $(Ta=25^{\circ}C, I_F=20mA)$ 

	(	,											•	, 1	. ,
Rank	XE	XF	XG	XH	XJ	XK	XL	XM	XN	XP	XQ	XR	XS	XT	XU
lv (mcd)	47~ 68	68~ 100	100~150	150~220	220~330	330~470	470~680	680~1000	1000~1500	1500~2200	2200~ 3300	3300~4700	4700~6800	6800~10000	10000~15000
SI A-570MT															

#### ■ Part No. Construction



#### ■ ATTENTION POINTS IN HANDLING

Visual light emitting diode does not contain reinforcement materials such as glass fillers. Therefore if sudden thermal and mechanical shock are given, destruction or inferiority of luminous intensity may occur. Please take care of the handling.

#### **■ FIXATION METHOD**

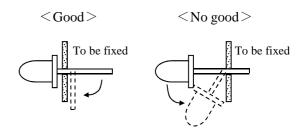
#### 1. ATTENTION POINTS

- (1) Please do not give excessive heat over storage temperature to resin.

  In case that the product has to be heated in oven for the glue fixing of surface mount parts, this LED should be mounted after the glue fixing.
- (2) Please avoid stress to resin at high temperature.

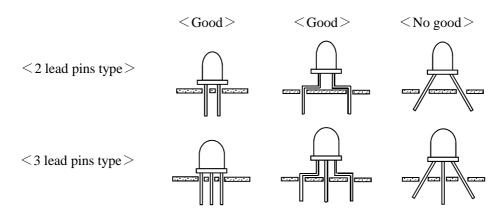
#### 2. TERMINATION PROCESSING

- (1) In case of termination processing, please fix the termination
- (2) Processing position, and process the reverse side of LED body.
  - If stress is given during processing, It may cause non-lighting failure.
- (3) Please process before soldering.



#### 3. ASSEMBLY ON PC BOARD

(1) In case of soldering on PCB, If the operation is done with stress, it may cause non-lighting failure during soldering or using. Please design the through-holes of PCB suitable for lead pins space or lead pins space after forming to avoid the physical stress on resin.



(2) Using spacer between LED's body and PCB is recommended.

In case of direct mount on PCB(SLR/SLI-343 series), please take care about clinch of LED pins to avoid the remained stress and solder heat stress.

Enough evaluation is requested before deciding assembly and soldering conditions.

Please consult with us if any problems in the evaluation stage.



#### 4. SOLDERING (Sn-3Ag-0.5Cu)

- (1) Please make soldering rapidly under the following temperature and time conditions.
- (2) Please avoid stress to LED lamp during soldering.
- (3) In case of double peak flow soldering, the temperature gap during 1st and 2nd soldering to be less than 100 degree C.

<Recommendable soldering conditions>

ARTI	CLE	SOLDERINGTEMP	OPERATION TIME	Remarks
	Pre-heat	Max. 100℃	60sec Max.	-
Soldering Dip	Soldering Bath	Max. 265℃	5sec Max.	In case of double peak flow soldering, the operation time is counted from the beginning of 1st peak to the end of 2nd peak.
Solderir	ig Iron	Max. 400℃	3sec Max.	The iron should not touch the LED's body.

#### 5. CLEANING

In case of cleaning, some solvents may cause damage of resin or cause non-lighting failure, so please check the solvent before actual use.

The recommendable cleaning solvent is alcoholic one such as isopropyl alcohol.

#### < RECOMMENDABLE CLEANING CONDITIONS>

METHOD	CONDITIONS
Cleaning by solvent	Temperature of solvent : Max. 45℃
Clearling by solvent	Immersion time : Max. 3min
Cleaning by solvent	Ultrasonic out : Max. 15W/Liter
Clearling by solvent	Cleaning time : Max. 3min

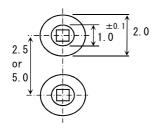
#### 6. RECOMMENDABLE ROUND PATTERN

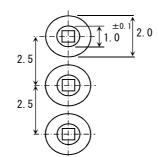
Round pattern depends on the material PCB, density and circuit arrangement. Our recommendation is as follow:

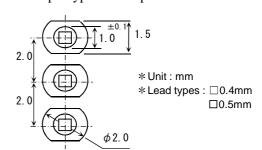
<2 lead pin type>

<3 lead pin type/2.5mm pitch>

< 3 lead pin type/2.0mm pitch>







#### ■ ATTENTION ON STORAGING

Storage in dry box is most desirable, but if it is not possible, we recommend following conditions.

#### <RECOMMENDABLE STORAGE CONDITIONS>

AR	ΓICLE	Temperature	Humidity	Expiration Date
COND	ITIONS	5~30℃	Max.60%RH	Within 1 year

Poor storage conditions may cause some failure as bellow.

- (1) Lead pins may corrode if it is stored in the environment of high temperature and humidity and lead to defective soldering.
- (2) In case of soldering after LED's body absorb moisture highly, destruction or inferiority of luminous intensity may occur.

#### ■ APPLICATION METHOD

- 1. Precaution for Drive System and Off Mode
  - •Design the circuit without the electric load exceeding the ABSOLUTE MAXIMUM RATING that applies on the products.
  - •If drive by constant voltage, it may cause current deviation of the LED and result in deviation of luminous intensity, so we recommend to drive by constant current. (Deviation of VF Value will cause deviation of current in LED.)
  - •Furthermore, for off mode, please do not apply voltage neither forward nor reverse. Especially, for the products with the Ag-paste used in the die bonding, there's high possibility to cause electro migration and result in function failure.

#### 2. Operation Life Span

There's possibility for intensity of light drop according to working conditions and environments (applied current, surrounding temperature and humidity, corrosive gases), please call our Sales staffs for inquiries about the concerned application below.

- (1) Longtime intensity of light life
- (2) On mode all the time

#### 3. Usage

The Product is LED. We are not responsible for the usage as the diode such as Protection Chip, Rectifier, Switching and so on.

#### **■**OTHERS

#### 1. Surrounding Gas

Notice that if it is stored under the condition of acid gas (chlorine gas, sulfured gas) or alkali gas (ammonia), it may result in low soldering ability (caused by the change in quality of the plating surface) or optical characteristics changes (light intensity, chrominance) and change in quality of die bonding (Ag-paste) materials. All of the above will cause function failure of the products. Therefore, please pay attention to the storage environment for mounted product (concern the generated gas of the surrounding parts of the products and the atmospheric environment).

#### 2. Electrostatic Damage

The product is part of semiconductor and electrostatic sensitive, there's high possibility to be damaged by the electrostatic discharge.

Please take appropriate measures to avoid the static electricity from human body and earthing setting of production equipment. The resistance values of electrostatic discharge (actual values) are different varies with products, therefore, please call our Sales staffs for inquiries.

#### 3. Electromagnetic Wave

Applications with strong electromagnetic wave such as, IH cooker, will influence the reliability of LED, therefore please evaluate before using it.

#### Notes

- 1) The information contained herein is subject to change without notice.
- Before you use our Products, please contact our sales representative and verify the latest specifications:
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM
- 4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.
- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
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http://www.rohm.com/contact/



# SLI-570DT - Web Page

Part Number	SLI-570DT
Package	SLI-570 / SLA-570
Unit Quantity	1000
Minimum Package Quantity	1000
Packing Type	Bulk
Constitution Materials List	inquiry
RoHS	Yes